

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE
PATENT APPLICATION TRANSMITTAL LETTER

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

Transmitted herewith for filing pursuant to 37 C.F.R. §1.53 is the patent application of:

INVENTORS:

Hatsuo ISHIDA
2903 Weybridge Road
Shaker Heights, Ohio 44120-1873

Koichi SHIBAYAMA
2-1 Hyakuyama Shimamoto-chou
Osaka 618-8589 JAPAN

Hiroshi ABE
c/o Sekisui Integrated Research, Inc.
3-5-24 Miyahara, Yodogawa-ku
Osaka 532-0003 JAPAN

FOR: A THERMOSETTING RESIN COMPOSITION AND ITS ARTICLE

Enclosed are:

- ☐ () sheets of drawings.
- ☐ An Assignment of the invention to: Sekisui Chemical Co., Ltd.
- ☐ An associate power of attorney.
- ☒ A Notice of Informal Filing of New Patent Application.
- ☒ A Japanese language Specification, Claims and Abstract.

The filing fee is calculated as follows:

	CLAIMS AS	FILED	SMALL ENTITY		OTHER THAN A SMALL ENTITY
FOR	NO. FILED	NO. EXTRA	RATE FEE		RATE FEE
BASIC FEE			\$375		\$ 770
Total Claims	16-20=	-0-	x9=	or	x18= -0-
Indep claims	8-3=	-5-	X43= -0-	or	x86= \$ 430
[] Multiple	Dep claims		+145= -0-	or	+290= -0-
			TOTAL		TOTAL \$1200

X Check in the amount of \$ 1200.00 is enclosed.

The Commissioner is hereby authorized to charge \$ to Deposit Account No. 20-1424 for the filing fee listed above.

The Commissioner is hereby authorized to charge \$ to the credit card identified in the attached Credit Card Payment Form for the filing fee listed above.

X The Commissioner is hereby authorized to charge payment of the following fees associated with this communication or credit any overpayment to Deposit Account No. 20-1424. A duplicate copy of this sheet is attached.

x Any additional fees under 37 CFR 1.16 for the presentation of extra claims.

x Any patent application processing fees under 37 CFR 1.17.

X The Commissioner is hereby authorized to charge payment of the following fees during the pendency of this application or credit any overpayment to Deposit Account No. 20-1424. A duplicate copy of this sheet is attached.

x Any patent application processing fees under 37 CFR 1.17, including extension of time fees.

x Any filing fees under 37 CFR 1.16 for the presentation of extra claims.

Respectfully submitted,

Donald E. Townsend, Jr.

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Reg. No. 43,198

Donald E. Townsend

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Reg. No. 22,069

Date: March 30, 2004

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:
H. Ishida, et al.

Serial No.: To Be Assigned

Art Unit: To Be Assigned

Filed: Concurrently Herewith

Examiner: To Be Assigned

For: A Thermosetting Resin Composition And Its Article

INFORMAL FILING OF NEW PATENT APPLICATION


Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

BOX PATENT APPLICATIONS

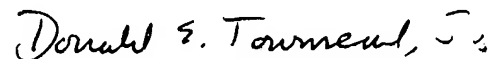
Sir:

The undersigned has been authorized by the Applicants, Hatsuo Ishida, Koichi Shibayama, and Hiroshi Abe, to file the enclosed patent application, and to defer filing of the Declaration/Power of Attorney.

Respectfully submitted,



Donald E. Townsend
Reg. No. 22,069



Donald E. Townsend, Jr.
Reg. No. 43,198

Date: March 30, 2004

Docket No.: FUJ-002-USA-P

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